



Material Content Data Sheet



Sales Product Name		ILD6070		Issued		26. September 2017		
MA#		MA001040756						
Package		PG-DSO-8-27		Weight*		84.08 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.018	2.40	2.40	24003	24003
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		108	
	non noble metal	zinc	7440-66-6	0.036	0.04		433	
	non noble metal	iron	7439-89-6	0.728	0.87		8655	
wire	non noble metal	copper	7440-50-8	29.548	35.14	36.06	351420	360616
	noble metal	gold	7440-57-5	0.194	0.23	0.23	2308	2308
	encapsulation	organic material	carbon black	1333-86-4	0.099	0.12		1176
plastics	plastics	epoxy resin	-	4.547	5.41		54079	
		silicondioxide	60676-86-0	44.778	53.25	58.78	532565	587820
leadfinish	non noble metal	tin	7440-31-5	0.695	0.83	0.83	8267	8267
plating	noble metal	silver	7440-22-4	0.725	0.86	0.86	8617	8617
glue	plastics	epoxy resin	-	0.176	0.21		2092	
		noble metal	silver	7440-22-4	0.528	0.63	0.84	6277
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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